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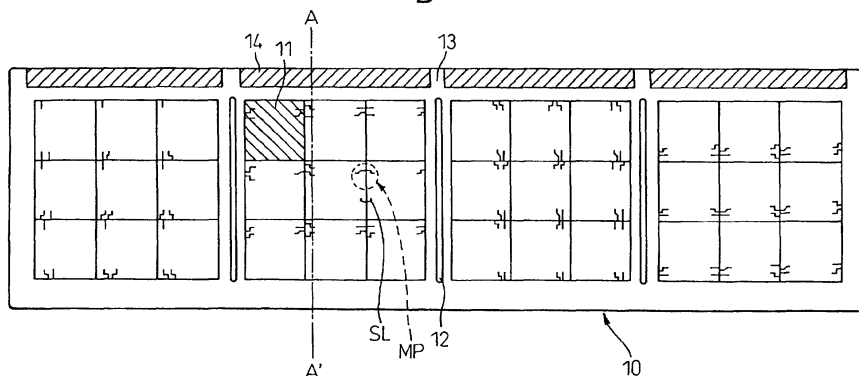
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(54) **Wiring substrate having position information**

(57) A wiring board for a semiconductor package comprises a base substrate having first and second surfaces; a wiring layer consisting of necessary wiring patterns formed on at least one of the first and second surfaces; a plurality of semiconductor element mounting areas formed on the surface of the base substrate on which the wiring layer is formed; and individual patterns

as position information provided for the respective semiconductor element mounting areas, the individual patterns having a particular shape for the respective semiconductor element mounting area. The individual patterns as position information are formed on peripheral regions of the respective semiconductor element mounting areas.

Fig.1



EP 1 280 204 A8